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(54) **PRINTED BOARD**

(57) Abstract:

PURPOSE: To obtain a printed board of excellent solderability on which the leads of an electronic component are set in position by a method wherein adjacent holes very close to each other on the board are connected to each other through a slit whose width is equal to a specified value or more end smaller than the length of minor axis of the hole.

CONSTITUTION: A printed board is composed of a printed board main body 1, a first and a second hole, 2 and 3, and a slit 4 which connects the holes 2 and 3 together. Here, the width a of the slit 4 is set larger than 0.5mm and smaller than the length of minor axis of the smaller hole (when the hole is not a right circle, the length of minor axis of the hole). In the substrate main body 1 structured as mentioned above, as the width a is made equal to 0.5mm or more, a die can retain its strength, where a molding die does not collapse or a punch is not broken. And, as the width a is made smaller than the length of short axis of the smaller hole, the slit 4 is small in width and the leads of an electronic component are set in position, and a metal foil provided around the holes is small in cutout, so that a printed board of this design is excellent in solderability.